Component	Weight	Material		Weight	Content
	[mg]	CAS No.	Name	[mg]	[%]
Chip	27.037	7440-21-3	Silicon	27.037	0.616
Frame	1841.616	-	Epoxy Resin	865.560	19.709
		7440-50-8	Copper	736.646	16.774
		-	Brominated Epoxy	184.162	4.193
		7440-02-0	Nickel	9.208	0.210
		7440-57-5	Gold	1.842	0.042
		-	Other	44.198	1.005
Die attach	3.400	7440-22-4	Silver	2.618	0.060
		-	Epoxy Resin	0.782	0.018
Wire bond	6.990	7440-57-5	Gold	6.990	0.159
Resin	1920.177	60676-86-0	Silica(fused)	1747.361	39.789
		-	Epoxy Resin	86.408	1.968
		-	Phenol Resin	86.408	1.968
Solder Ball	592.400	7440-31-5	Tin	571.666	13.017
		7440-22-4	Silver	17.772	0.405
		7440-50-8	Copper	2.962	0.067
Total Weight	4391.620			4391.620	100.000